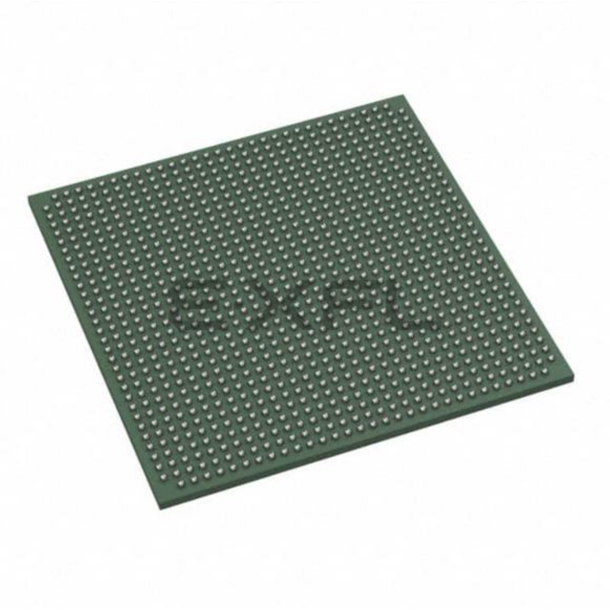


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga40e-5ff1020i

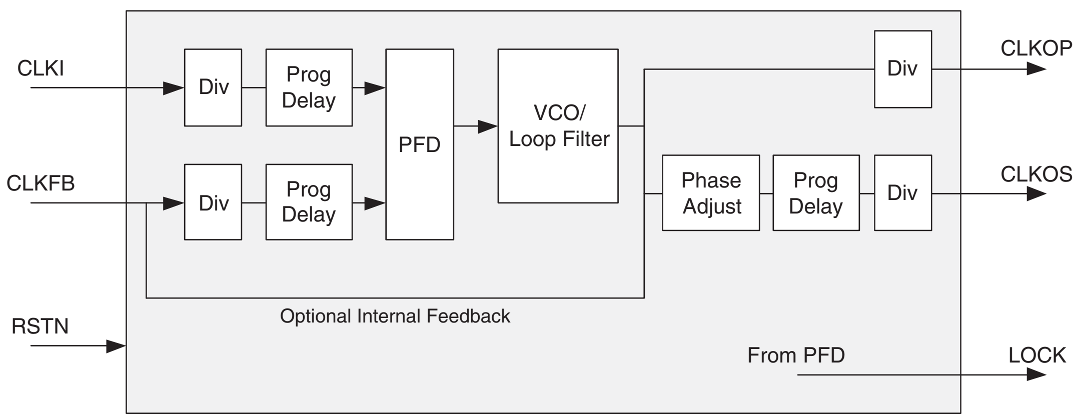
The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically.

The Phase Select block can modify the phase of the clock signal if desired. The Spread Spectrum block supports the modulation of the PLL output frequency. This reduces the peak energy in the fundamental and its harmonics providing for lower EMI (Electro Magnetic Interference).

The sysCLOCK PLL can be configured at power-up and then, if desired, reconfigured dynamically through the serial memory interface bus which connects with the on-chip system bus. For example, the user can select inputs, loop filters, divider setting, delay settings and phase shift settings. The user can also directly access the SMI bus through the routing.

The PLL clock input, from pin or routing, feeds into an input divider. There are four sources of feedback signal to the feedback divider: from the clock net, directly from the voltage controlled oscillator (VCO) output, from the routing or from an external pin. The signal from the input clock divider and the feedback divider are passed through the programmable delay before entering the phase frequency detector (PFD) unit. The output of this PFD is used to control the voltage controlled oscillator. There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-11 shows the sysCLOCK PLL diagram.

Figure 2-11. PLL Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Spread Spectrum Clocking (SSC)

The PLL supports spread spectrum clocking to reduce peak EMI by using “down-spread” modulation. The spread spectrum operation will vary the output frequency (at 30KHz to 500KHz) in a range that is between its nominal value, down to a frequency that is a programmable 1%, 2%, or 3% lower than normal.

Digital Locked Loop (DLLs)

In addition to PLLs, the LatticeSC devices have up to 12 DLLs per device. DLLs assist in the management of clocks and strobes. DLLs are well suited to applications where the clock may be stopped or transferring jitter from input to output is important, for example forward clocked interfaces. PLLs are good for applications requiring the lowest output jitter or jitter filtering. All DLL outputs are routed as primary/edge clock sources.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. LOCK output signal is asserted when the DLL is locked. The ALU HOLD signal setting allows users to freeze the DLL at its current delay setting.

Table 2-6. Input/Output/Tristate Gearing Resource Rules

PIO	Input/Output Logic			Tri-State/Bidi	
	x1	x2	x4	x1	x2/x4
A	?	?	?	?	N/A
B	?	No I/O Logic	No I/O Logic	?	N/A
C	?	?	No I/O Logic	?	N/A
D	?	No I/O Logic	No I/O Logic	?	N/A

Note: Pin can still be used without I/O logic.

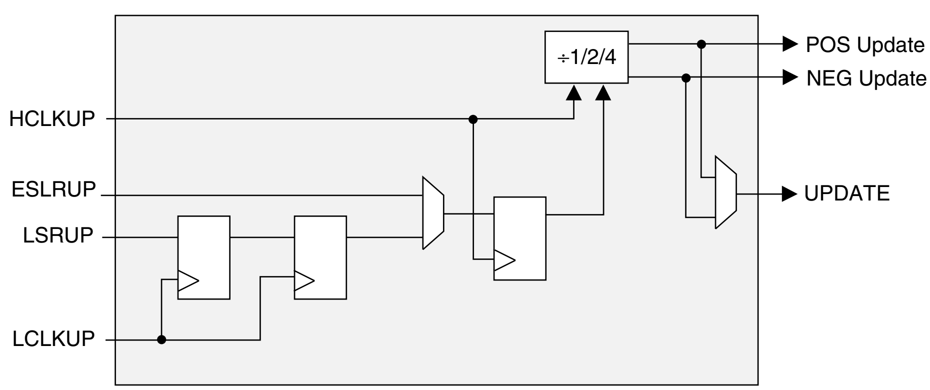
Control Logic Block

The control logic block allows the modification of control signals selected by the routing before they are used in the PIO. It can optionally invert all signals passing through it except the Global Set/Reset. Global Set/Reset can be enabled or disabled. It can route either the edge clock or the clock to the high-speed clock nets. The clock provided to the PIO by routing is used as the slow-speed clocks. In addition this block contains delays that can be inserted in the clock nets to enable Lattice's unique cycle boosting capability.

Update Block

The update block is used to generate the POS update and NEG update signals used by the DDR/Shift register blocks within the PIO. Note the update block is only required in shift modes. This is required in order to do the high speed to low speed handoff. One of these update signals is also selected and output from the PIC as the signal UPDATE. It consists of a shift chain that operates off either the high-speed input or output clock. The values of each register in the chain are set or reset depending on the desired mode of operation. The set/reset signal is generated from either the edge reset ELSR or the local reset LSR. These signals are optionally inverted by the Control Logic Block and provided to the update block as ELSRUP and LSRUP. The Lattice design tools automatically configure and connect the update block when one of the DDR or shift register primitives is used.

Figure 2-25. Update Block



PURESPEED I/O Buffer

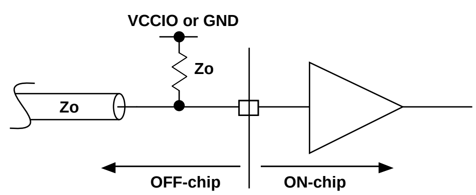
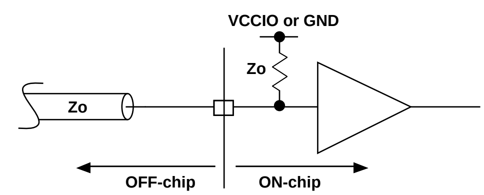
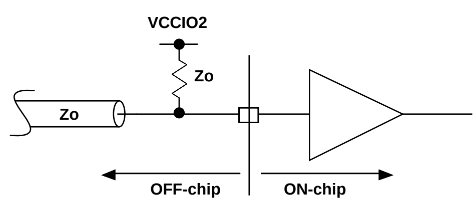
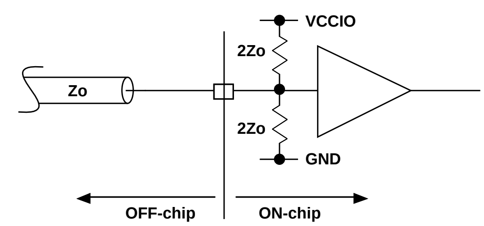
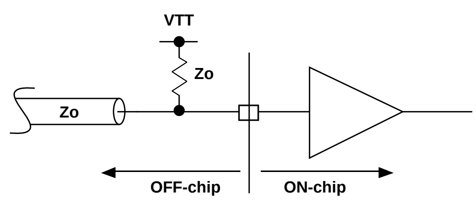
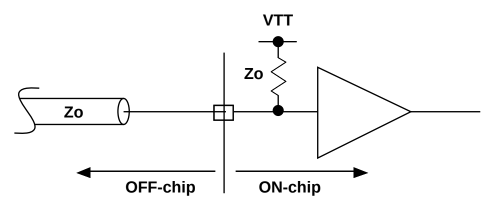
Each I/O is associated with a flexible buffer referred to as PURESPEED I/O buffer. These buffers are arranged around the periphery of the device in seven groups referred to as Banks. The PURESPEED I/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL. The availability of programmable on-chip termination for both input and output use, further enhances the utility of these buffers.

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:

VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:

If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply

All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table[1]

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 1000BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

flexiPCS quads are not dedicated solely to industry standard protocols. Each quad (and each channel within a quad) can be programmed for many user defined data manipulation modes. For example, modes governing user-defined word alignment and multi-channel alignment can be programmed for non-standard protocol applications.

For more information on the functions and use of the flexiPCS, refer to the LatticeSC/M Family flexiPCS Data Sheet.

System Bus

Each LatticeSC device connects the FPGA elements with a standardized bus framework referred to as a System Bus. Multiple bus masters optimize system performance by sharing resources between different bus masters such as the MPI and configuration logic. The wide data bus configuration of 32 bits with 4-bit parity supports high-bandwidth, data intensive applications.

There are two types of interfaces on the System Bus, master and slave. A master interface has the ability to perform actions on the bus, such as writes and reads to and from a specific address. A slave interface responds to the actions of a master by accepting data and address on a write and providing data on a read. The System Bus has a memory map which describes each of the slave peripherals that is connected on the bus. Using the addresses listed in the memory map, a master interface can access each of the slave peripherals on the System Bus. Any and all peripherals on the System Bus can be used at the same time. Table 2-12 list all of the available user peripherals on the System Bus after device power-up.

Table 2-12. System Bus User Peripherals

Peripheral	Name	Interface Type
Micro Processor Interface	MPI	Master
User Master Interface	UMI	Master
User Slave Interface	USI	Slave
Serial Management Interface (PLL, DLL, User Logic)	SMI	Slave
Physical Coding Sublayer	PCS	Slave
Direct FPGA Access	DFA	Slave

The peripherals listed in Table 2-12 can be added when the System Bus module is created using Module IP/Manager (ispLEVER Module/IP Manager).

Figure 2-31 also lists the existing peripherals on the System Bus. The gray boxes are available only during configuration. Refer to Lattice technical note TN1080, LatticeSC sysCONFIG Usage Guide, for configuration options. The Status and Config box refers to internal System Bus registers. This document presents all the interfaces listed in Table 2-12 in detail to help the user utilize the desired functions of the System Bus.

PURESPEED I/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold ($Q-\overline{Q}$)		+/-100	—	—	mV
V_{CM}	Input common mode voltage		0.05	1.2	2.35	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125	1.20	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{SAB}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	12	mA
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps	T_R, T_F

Notes:
1. Data is for 3.5mA differential current drive. Other differential driver current options are available.
2. If the low power mode of the input buffer is used, the minimum V_{CM} is 600 mV.

Mini-LVDS

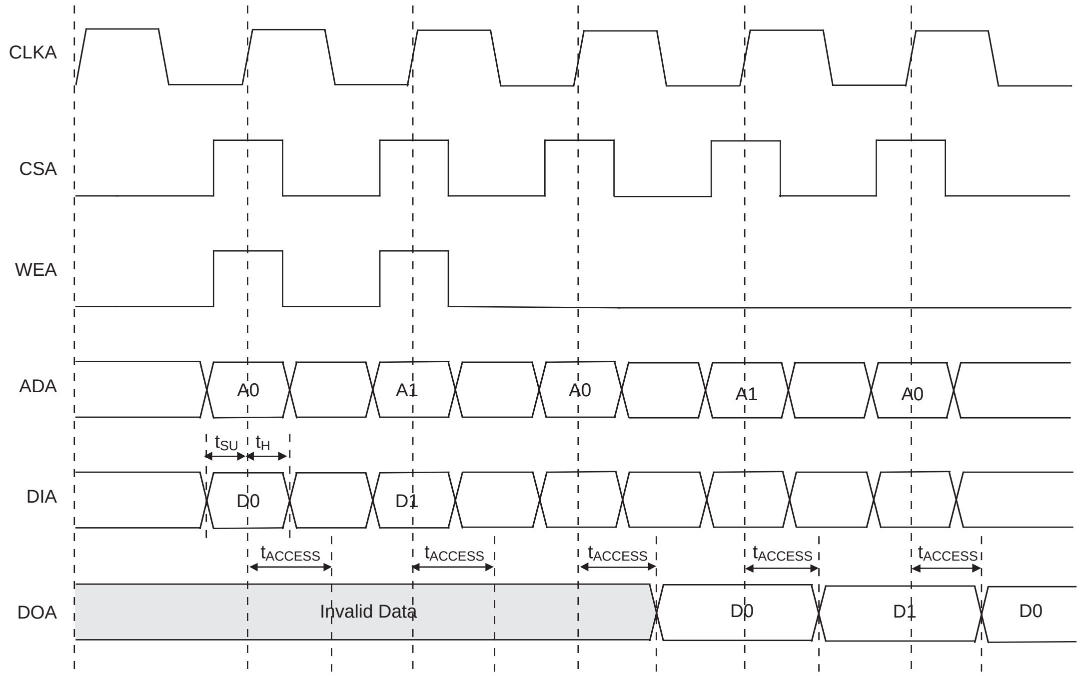
Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
Z_O	Single-ended PCB trace impedance	30	50	75	ohms
R_T	Differential termination resistance	60	100	150	ohms
V_{OD}	Output voltage, differential, $\lvert V_{OP} - V_{OM}\rvert$	300	—	600	mV
V_{OS}	Output voltage, common mode, $\lvert V_{OP} + V_{OM}\rvert/2$	1	1.2	1.4	V
ΔV_{OD}	Change in V_{OD}, between H and L	—	—	50	mV
ΔV_{ID}	Change in V_{OS}, between H and L	—	—	50	mV
V_{THD}	Input voltage, differential, $\lvert V_{INP} - V_{INM}\rvert$	200	—	600	mV
V_{CM}	Input voltage, common mode, $\lvert V_{INP} + V_{INM}\rvert/2$	0.3+(V_{THD}/2)	—	2.1-(V_{THD}/2)	
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps
T_{ODUTY}	Output clock duty cycle	45	—	55	%
T_{IDUTY}	Input clock duty cycle	40	—	60	%

Note: Data is for 6mA differential current drive. Other differential driver current options are available.

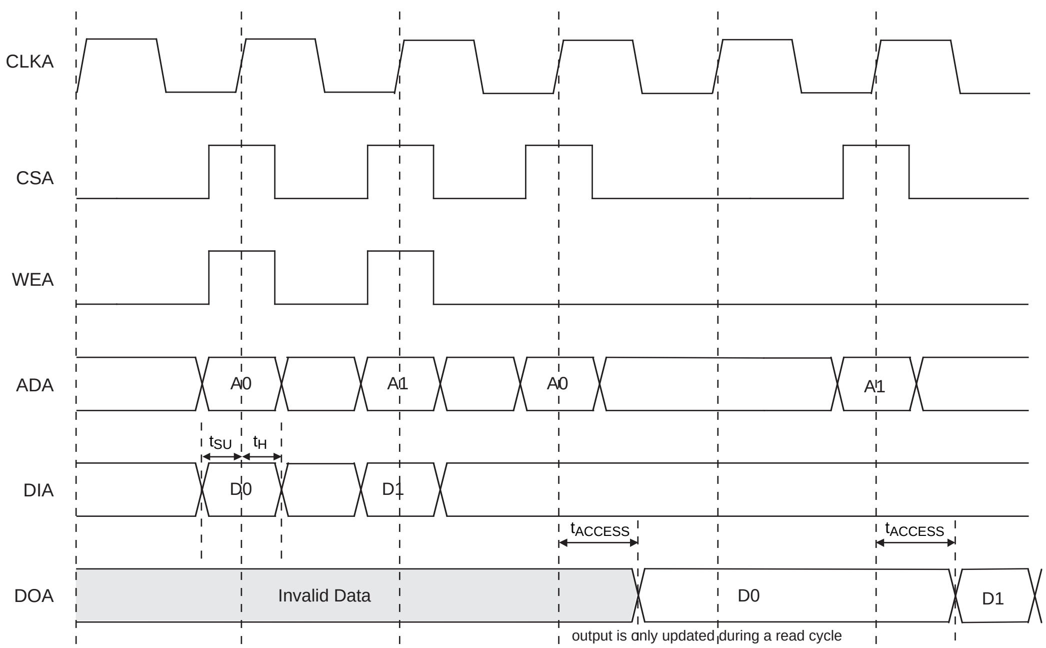
EBR Memory Timing Diagrams

Figure 3-6. Read Mode



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-7. Read Mode with Input Registers Only



Signal Descriptions (Cont.)

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
Multi-chip Alignment (User I/O if not used.)		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
Miscellaneous Dedicated Pins		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
SERDES Block (Dedicated Pins)		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y9	VCCIO6	-		VCCIO6	-	
J7	VCCIO7	-		VCCIO7	-	
J8	VCCIO7	-		VCCIO7	-	
K7	VCCIO7	-		VCCIO7	-	
K8	VCCIO7	-		VCCIO7	-	
L8	VCCIO7	-		VCCIO7	-	
L9	VCCIO7	-		VCCIO7	-	
M9	VCCIO7	-		VCCIO7	-	
N9	VCCIO7	-		VCCIO7	-	
P9	VCCIO7	-		VCCIO7	-	
R9	VCCIO7	-		VCCIO7	-	
A1	GND	-		GND	-	
A30	GND	-		GND	-	
AA15	GND	-		GND	-	
AA16	GND	-		GND	-	
AK1	GND	-		GND	-	
AK30	GND	-		GND	-	
K15	GND	-		GND	-	
K16	GND	-		GND	-	
L11	GND	-		GND	-	
L12	GND	-		GND	-	
L13	GND	-		GND	-	
L14	GND	-		GND	-	
L15	GND	-		GND	-	
L16	GND	-		GND	-	
L17	GND	-		GND	-	
L18	GND	-		GND	-	
L19	GND	-		GND	-	
L20	GND	-		GND	-	
M11	GND	-		GND	-	
M12	GND	-		GND	-	
M13	GND	-		GND	-	
M14	GND	-		GND	-	
M15	GND	-		GND	-	
M16	GND	-		GND	-	
M17	GND	-		GND	-	
M18	GND	-		GND	-	
M19	GND	-		GND	-	
M20	GND	-		GND	-	
N11	GND	-		GND	-	
N12	GND	-		GND	-	
N13	GND	-		GND	-	
N14	GND	-		GND	-	
N15	GND	-		GND	-	
N16	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B30	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
D30	A_VDDOB0_L	-		A_VDDOB0_L	-	
A30	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
C31	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
C32	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
B31	A_VDDIB0_L	-		A_VDDIB0_L	-	
AL25	NC	-		PB26A	5	
AL24	NC	-		PB26B	5	
AG27	NC	-		PB26C	5	
AH27	NC	-		PB26D	5	
AM25	NC	-		PB27A	5	
AM24	NC	-		PB27B	5	
AL9	NC	-		PB62A	4	
AL8	NC	-		PB62B	4	
AK9	NC	-		PB63A	4	
AJ9	NC	-		PB63B	4	
AG10	NC	-		PB63C	4	
AG11	NC	-		PB63D	4	
J30	NC	-		PL26A	7	
H30	NC	-		PL26B	7	
M28	NC	-		PL26C	7	
N28	NC	-		PL26D	7	
J32	NC	-		PL27A	7	
J31	NC	-		PL27B	7	
N26	NC	-		PL27C	7	
N27	NC	-		PL27D	7	
K31	NC	-		PL29A	7	
K32	NC	-		PL29B	7	
P25	NC	-		PL29C	7	
P26	NC	-		PL29D	7	
L27	NC	-		PL22C	7	
L28	NC	-		PL22D	7	
M29	NC	-		PL30A	7	
L29	NC	-		PL30B	7	
M30	NC	-		PL31A	7	
L30	NC	-		PL31B	7	
L31	NC	-		PL34A	7	
M31	NC	-		PL34B	7	
AA29	NC	-		PL56A	6	
AA30	NC	-		PL56B	6	
AB31	NC	-		PL57A	6	
AA31	NC	-		PL57B	6	
AG30	NC	-		PL57C	6	
AG29	NC	-		PL57D	6	
AB29	NC	-		PL58A	6	
AB30	NC	-		PL58B	6	
Y25	NC	-		PL58C	6	
AA25	NC	-		PL58D	6	
AA8	NC	-		PR58D	3	
Y8	NC	-		PR58C	3	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AA7	VCCIO3	-		VCCIO3	-	
AB9	VCCIO3	-		VCCIO3	-	
AC4	VCCIO3	-		VCCIO3	-	
AD6	VCCIO3	-		VCCIO3	-	
AF3	VCCIO3	-		VCCIO3	-	
T3	VCCIO3	-		VCCIO3	-	
U4	VCCIO3	-		VCCIO3	-	
V6	VCCIO3	-		VCCIO3	-	
W10	VCCIO3	-		VCCIO3	-	
Y3	VCCIO3	-		VCCIO3	-	
AC11	VCCIO4	-		VCCIO4	-	
AD14	VCCIO4	-		VCCIO4	-	
AF15	VCCIO4	-		VCCIO4	-	
AF9	VCCIO4	-		VCCIO4	-	
AG12	VCCIO4	-		VCCIO4	-	
AJ13	VCCIO4	-		VCCIO4	-	
AJ7	VCCIO4	-		VCCIO4	-	
AK10	VCCIO4	-		VCCIO4	-	
AK16	VCCIO4	-		VCCIO4	-	
AK4	VCCIO4	-		VCCIO4	-	
AC19	VCCIO5	-		VCCIO5	-	
AD22	VCCIO5	-		VCCIO5	-	
AF21	VCCIO5	-		VCCIO5	-	
AG18	VCCIO5	-		VCCIO5	-	
AG24	VCCIO5	-		VCCIO5	-	
AJ17	VCCIO5	-		VCCIO5	-	
AJ23	VCCIO5	-		VCCIO5	-	
AJ30	VCCIO5	-		VCCIO5	-	
AK20	VCCIO5	-		VCCIO5	-	
AK26	VCCIO5	-		VCCIO5	-	
AA27	VCCIO6	-		VCCIO6	-	
AB23	VCCIO6	-		VCCIO6	-	
AC30	VCCIO6	-		VCCIO6	-	
AD26	VCCIO6	-		VCCIO6	-	
AF29	VCCIO6	-		VCCIO6	-	
T29	VCCIO6	-		VCCIO6	-	
U30	VCCIO6	-		VCCIO6	-	
V26	VCCIO6	-		VCCIO6	-	
W24	VCCIO6	-		VCCIO6	-	
Y29	VCCIO6	-		VCCIO6	-	
G30	VCCIO7	-		VCCIO7	-	
J27	VCCIO7	-		VCCIO7	-	
K29	VCCIO7	-		VCCIO7	-	
L24	VCCIO7	-		VCCIO7	-	
M26	VCCIO7	-		VCCIO7	-	
N30	VCCIO7	-		VCCIO7	-	
P23	VCCIO7	-		VCCIO7	-	
R27	VCCIO7	-		VCCIO7	-	
AA11	VCCAUX	-		VCCAUX	-	
AA12	VCCAUX	-		VCCAUX	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
U12	VCC12	-		VCC12	-	
U21	VCC12	-		VCC12	-	
AA16	VCC12	-		VCC12	-	
AA17	VCC12	-		VCC12	-	
M14	VCC12	-		VCC12	-	
P12	VCC12	-		VCC12	-	
W12	VCC12	-		VCC12	-	
AA14	VCC12	-		VCC12	-	
AA19	VCC12	-		VCC12	-	
W21	VCC12	-		VCC12	-	
P21	VCC12	-		VCC12	-	
M19	VCC12	-		VCC12	-	
A2	GND	-		GND	-	
A10	GND	-		GND	-	
E28	NC	-		NC	-	
E5	NC	-		NC	-	
F10	NC	-		NC	-	
E10	NC	-		NC	-	
E23	NC	-		NC	-	
F23	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M25 and LatticeSC/M40 in a 1020-pin package support a 16-bit MPI interface.

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF21	PB26D	5		PB29D	5	
AN23	PB27A	5		PB45A	5	
AN22	PB27B	5		PB45B	5	
AP23	PB29A	5		PB55A	5	
AP22	PB29B	5		PB55B	5	
AG21	PB29C	5		PB55C	5	
AG20	PB29D	5		PB55D	5	
AP25	PB30A	5	PCLKT5_3	PB48A	5	PCLKT5_3
AP24	PB30B	5	PCLKC5_3	PB48B	5	PCLKC5_3
AD21	PB30C	5	PCLKT5_4	PB48C	5	PCLKT5_4
AD20	PB30D	5	PCLKC5_4	PB48D	5	PCLKC5_4
AL23	PB31A	5	PCLKT5_5	PB49A	5	PCLKT5_5
AL22	PB31B	5	PCLKC5_5	PB49B	5	PCLKC5_5
AH24	PB31C	5		PB49C	5	
AH23	PB31D	5		PB49D	5	
AM23	PB33A	5	PCLKT5_0	PB51A	5	PCLKT5_0
AM22	PB33B	5	PCLKC5_0	PB51B	5	PCLKC5_0
AJ24	PB33C	5		PB51C	5	
AJ23	PB33D	5	VREF2_5	PB51D	5	VREF2_5
AN21	PB34A	5	PCLKT5_1	PB52A	5	PCLKT5_1
AN20	PB34B	5	PCLKC5_1	PB52B	5	PCLKC5_1
AE19	PB34C	5	PCLKT5_6	PB52C	5	PCLKT5_6
AD19	PB34D	5	PCLKC5_6	PB52D	5	PCLKC5_6
AK21	PB35A	5	PCLKT5_2	PB53A	5	PCLKT5_2
AK20	PB35B	5	PCLKC5_2	PB53B	5	PCLKC5_2
AK23	PB35C	5	PCLKT5_7	PB53C	5	PCLKT5_7
AK22	PB35D	5	PCLKC5_7	PB53D	5	PCLKC5_7
AL20	PB37A	5		PB56A	5	
AL19	PB37B	5		PB56B	5	
AG19	PB37C	5		PB56C	5	
AF19	PB37D	5		PB56D	5	
AP21	PB38A	5		PB57A	5	
AP20	PB38B	5		PB57B	5	
AH21	PB38C	5		PB57C	5	
AH20	PB38D	5		PB57D	5	
AM20	PB39A	5		PB59A	5	
AM19	PB39B	5		PB59B	5	
AJ21	PB39C	5		PB59C	5	
AJ20	PB39D	5		PB59D	5	
AK19	PB41A	5		PB60A	5	
AK18	PB41B	5		PB60B	5	
AE18	PB41C	5		PB60C	5	
AD18	PB41D	5		PB60D	5	
AN19	PB42A	5		PB61A	5	
AN18	PB42B	5		PB61B	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
V8	PR65D	3	PCLKC3_3
U8	PR65C	3	PCLKT3_3
U5	PR65B	3	
T5	PR65A	3	
V6	PR64D	3	PCLKC3_1
U6	PR64C	3	PCLKT3_1
T4	PR64B	3	PCLKC3_0
T3	PR64A	3	PCLKT3_0
U9	PR62D	2	PCLKC2_2
T9	PR62C	2	PCLKT2_2
R2	PR62B	2	PCLKC2_0
P2	PR62A	2	PCLKT2_0
T11	PR61D	2	PCLKC2_3
U11	PR61C	2	PCLKT2_3
R4	PR61B	2	PCLKC2_1
R3	PR61A	2	PCLKT2_1
T8	PR60D	2	
R8	PR60C	2	
P1	PR60B	2	
N1	PR60A	2	
R6	PR57D	2	
P6	PR57C	2	
M1	PR57B	2	
L1	PR57A	2	
T10	PR56D	2	
U10	PR56C	2	
N2	PR56B	2	
M2	PR56A	2	
R11	PR51D	2	
P11	PR51C	2	
N4	PR51B	2	
M4	PR51A	2	
N5	PR49D	2	
M5	PR49C	2	
L2	PR49B	2	
K2	PR49A	2	
P8	PR47D	2	
N8	PR47C	2	
J2	PR47B	2	
H2	PR47A	2	
M6	PR45D	2	
L6	PR45C	2	
K3	PR45B	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

	LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function
AL5	GND	-	
AM14	GND	-	
AM18	GND	-	
AM24	GND	-	
AM30	GND	-	
AM8	GND	-	
AN1	GND	-	
AN34	GND	-	
AP2	GND	-	
AP33	GND	-	
B1	GND	-	
B34	GND	-	
C11	GND	-	
C12	GND	-	
C13	GND	-	
C14	GND	-	
C17	GND	-	
C21	GND	-	
C22	GND	-	
C23	GND	-	
C24	GND	-	
C26	GND	-	
C27	GND	-	
C30	GND	-	
C31	GND	-	
C4	GND	-	
C5	GND	-	
C8	GND	-	
C9	GND	-	
D18	GND	-	
E32	GND	-	
E4	GND	-	
F19	GND	-	
G16	GND	-	
G29	GND	-	
G7	GND	-	
H3	GND	-	
H31	GND	-	
J10	GND	-	
J15	GND	-	
J26	GND	-	
K20	GND	-	
K23	GND	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
R12	VTT_2	2	
T12	VTT_2	2	
AB11	VTT_3	3	
W12	VTT_3	3	
Y12	VTT_3	3	
AC15	VTT_4	4	
AC16	VTT_4	4	
AD13	VTT_4	4	
AC19	VTT_5	5	
AC20	VTT_5	5	
AD22	VTT_5	5	
AB24	VTT_6	6	
W23	VTT_6	6	
Y23	VTT_6	6	
N24	VTT_7	7	
R23	VTT_7	7	
T23	VTT_7	7	
M12	VDDAX25_R	-	
M23	VDDAX25_L	-	
Y16	GND	-	
Y14	GND	-	
N21	VCC12	-	
P22	VCC12	-	
AA22	VCC12	-	
AB21	VCC12	-	
AB14	VCC12	-	
AA13	VCC12	-	
P13	VCC12	-	
N14	VCC12	-	
G26	NC	-	
G9	NC	-	
J12	NC	-	
H12	NC	-	
H23	NC	-	
J23	NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).
2. The LatticeSC/M115 in an 1152-pin package supports a 32-bit MPI interface.

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C33	GND	-		GND	-	
C35	GND	-		GND	-	
C36	GND	-		GND	-	
C39	GND	-		GND	-	
C4	GND	-		GND	-	
C40	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
D15	GND	-		GND	-	
D21	GND	-		GND	-	
D25	GND	-		GND	-	
D31	GND	-		GND	-	
F4	GND	-		GND	-	
F40	GND	-		GND	-	
G11	GND	-		GND	-	
G17	GND	-		GND	-	
G26	GND	-		GND	-	
G32	GND	-		GND	-	
H14	GND	-		GND	-	
H20	GND	-		GND	-	
H23	GND	-		GND	-	
H29	GND	-		GND	-	
H35	GND	-		GND	-	
H8	GND	-		GND	-	
J3	GND	-		GND	-	
J39	GND	-		GND	-	
L16	GND	-		GND	-	
L27	GND	-		GND	-	
L36	GND	-		GND	-	
L7	GND	-		GND	-	
M19	GND	-		GND	-	
M24	GND	-		GND	-	
M4	GND	-		GND	-	
M40	GND	-		GND	-	
N12	GND	-		GND	-	
N31	GND	-		GND	-	
P35	GND	-		GND	-	
P8	GND	-		GND	-	
R15	GND	-		GND	-	
R28	GND	-		GND	-	
R3	GND	-		GND	-	
R39	GND	-		GND	-	
T11	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V21	VCC	-		VCC	-	
V22	VCC	-		VCC	-	
V23	VCC	-		VCC	-	
V25	VCC	-		VCC	-	
V27	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
W22	VCC	-		VCC	-	
W24	VCC	-		VCC	-	
W26	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
Y23	VCC	-		VCC	-	
Y25	VCC	-		VCC	-	
Y27	VCC	-		VCC	-	
AG22	VCC12	-		VCC12	-	
AG26	VCC12	-		VCC12	-	
T17	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	
T22	VCC12	-		VCC12	-	
T26	VCC12	-		VCC12	-	
U16	VCC12	-		VCC12	-	
U27	VCC12	-		VCC12	-	
AC15	VCCAUX	-		VCCAUX	-	
AC28	VCCAUX	-		VCCAUX	-	
AD15	VCCAUX	-		VCCAUX	-	
AD28	VCCAUX	-		VCCAUX	-	
AE15	VCCAUX	-		VCCAUX	-	
AE28	VCCAUX	-		VCCAUX	-	
AF15	VCCAUX	-		VCCAUX	-	
AF28	VCCAUX	-		VCCAUX	-	
AG15	VCCAUX	-		VCCAUX	-	
AG28	VCCAUX	-		VCCAUX	-	
AH14	VCCAUX	-		VCCAUX	-	
AH16	VCCAUX	-		VCCAUX	-	
AH17	VCCAUX	-		VCCAUX	-	
AH18	VCCAUX	-		VCCAUX	-	
AH19	VCCAUX	-		VCCAUX	-	
AH20	VCCAUX	-		VCCAUX	-	
AH23	VCCAUX	-		VCCAUX	-	
AH24	VCCAUX	-		VCCAUX	-	
AH25	VCCAUX	-		VCCAUX	-	
AH26	VCCAUX	-		VCCAUX	-	

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
			Removed Read-Before-Write sysMEM EBR mode.
December 2008	02.2	Architecture	Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
		DC and Switching Characteristics	DC and Switching Characteristics table - updated data for t_{SUI_PIO}.
			Added T_R, T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
		Multiple	Removed references to HyperTransport throughout the data sheet.
January 2010	02.3	Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	